

PCN Number:	20230215000.2		PCN Date:	February 16, 2023																			
Title:	Qualification of CFAB as an additional Fab Site																						
Customer Contact:	PCN Manager		Dept:	Quality Services																			
Proposed 1st Ship Date:	Aug 15, 2023		Sample requests accepted until:	Mar 18, 2023*																			
*Sample requests received after Mar 18, 2023 will not be supported.																							
Change Type:																							
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Assembly Materials																		
<input type="checkbox"/>	Design	<input type="checkbox"/>	Electrical Specification	<input type="checkbox"/>	Mechanical Specification																		
<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process																		
<input type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Material	<input type="checkbox"/>	Wafer Bump Process																		
<input checked="" type="checkbox"/>	Wafer Fab Site	<input checked="" type="checkbox"/>	Wafer Fab Materials	<input type="checkbox"/>	Wafer Fab Process																		
		<input type="checkbox"/>	Part number change																				
PCN Details																							
Description of Change:																							
Qualification of CFAB as an additional Fab site using qualified Process Technology.																							
<table border="1"> <thead> <tr> <th colspan="3">Current Fab Site</th> <th colspan="3">Additional Fab Site</th> </tr> <tr> <th>Current Fab Site</th> <th>Process</th> <th>Wafer Diameter</th> <th>Additional Fab Site</th> <th>Process</th> <th>Wafer Diameter</th> </tr> </thead> <tbody> <tr> <td>DL-LIN</td> <td>LBC3S</td> <td>150mm</td> <td>CFAB</td> <td>LBC3S</td> <td>200mm</td> </tr> </tbody> </table>						Current Fab Site			Additional Fab Site			Current Fab Site	Process	Wafer Diameter	Additional Fab Site	Process	Wafer Diameter	DL-LIN	LBC3S	150mm	CFAB	LBC3S	200mm
Current Fab Site			Additional Fab Site																				
Current Fab Site	Process	Wafer Diameter	Additional Fab Site	Process	Wafer Diameter																		
DL-LIN	LBC3S	150mm	CFAB	LBC3S	200mm																		
Qual details are provided in the Qual Data Section.																							
Reason for Change:																							
These changes are part of our multiyear plan to transition products from our 150-millimeter factories to newer, more efficient manufacturing processes and technologies, underscoring our commitment to product longevity and supply continuity.																							
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):																							
None																							
Impact on Environmental Ratings																							
Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.																							
<table border="1"> <thead> <tr> <th>RoHS</th> <th>REACH</th> <th>Green Status</th> <th>IEC 62474</th> </tr> </thead> <tbody> <tr> <td><input checked="" type="checkbox"/> No Change</td> <td><input checked="" type="checkbox"/> No Change</td> <td><input checked="" type="checkbox"/> No Change</td> <td><input checked="" type="checkbox"/> No Change</td> </tr> </tbody> </table>						RoHS	REACH	Green Status	IEC 62474	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change										
RoHS	REACH	Green Status	IEC 62474																				
<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change																				
Changes to product identification resulting from this PCN:																							
Fab Site Information:																							
Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City																				
DL-LIN	DLN	USA	Dallas																				
CFAB	CU3	CHN	Chengdu																				
Sample product shipping label (not actual product label)																							



MADE IN: Malaysia
2DC: 20:



MSL 2 / 260C/1 YEAR SEAL DT
MSL 1 / 235C/UNLIM 03/29/04

OPT:
ITEM: 39
LBL: 5A (L)T0:1750

(1P) SN74LS07NSR
(Q) 2000 (D) 0336
(31T) LOT: 3959047MLA
(4W) TKY (1T) 7523483SI2
(P)
(2P) REV: (V) 0033317
(20L) GSO: SHE (21L) CCO:USA
(22L) ASO: MLA (23L) ACO: MYS

Product Affected:

TLC2272AIP

TLV2252AIPWR

For alternate parts with similar or improved performance, please visit the product page on TI.com



TI Information
Selective Disclosure

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: TLC2264AQPWRQ1	Qual Device: TLC2264AIDRCT	QBS Process Reference: CD3301RHR	QBS Package Reference: TLV9064QPWRQ1
HTOL	Life Test, 150C	300 Hours	1/3/0	-	3/231/0	-
HTSL	High Temp Storage Bake 170C	420 Hours	-	-	3/231/0	1/45/0
HAST	Biased HAST, 130C/85%RH	96 Hours	-	-	3/231/0	-
AC	Autoclave 121C	96 Hours	-	-	3/231/0	3/231/0
TC	Temperature Cycle, -65/150C	500 Cycles	-	-	3/231/0	3/231/0
HBM	ESD - HBM	2000 V	1/3/0	-	1/3/0	-
CDM	ESD - CDM	750 V	1/3/0	-	1/3/0	-
LU	Latch-up	(per JESD78)	1/6/0	-	1/6/0	-
ED	Electrical Characterization	Per Datasheet Parameters	1/30/0	-	1/30/0	-
MQ	Assembly MQ	Per Site Specifications	Pass	Pass	Pass	Pass

- QBS: Qual By Similarity
- Qual Device TLC2264AQPWRQ1 is qualified at LEVEL1-260C
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

TI Qualification ID: 20200903-135990

Qualification Results
Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: TLV2464CPWR	QBS Process Reference: CD3301RHHR	QBS Package Reference: TPS2042BD	QBS Package Reference: TPS2419DR
HTOL	Life Test, 150C	300 Hours	-	3/231/0	-	-
HTSL	High Temp Storage Bake 170C	420 Hours	-	3/231/0	3/231/0	3/231/0
HAST	Biased HAST, 130C/85%RH	96 Hours	-	3/231/0	-	3/231/0
AC	Autoclave 121C	96 Hours	-	3/231/0	3/231/0	3/231/0
TC	Temperature Cycle, -65/150C	500 Cycles	-	3/231/0	3/231/0	3/231/0
HBM	ESD - HBM	4000 V	1/3/0	1/3/0	-	-
CDM	ESD - CDM	1000 V	1/3/0	1/3/0	-	-
LU	Latch-up	(per JESD78)	1/6/0	1/6/0	-	-
ED	Electrical Characterization	Per Datasheet Parameters	1/30/0	1/30/0	-	-
MQ	Assembly MQ	Per Site Specifications	Pass	Pass	Pass	Pass

- QBS: Qual By Similarity
 - Qual Device TLV2464CPWR is qualified at LEVEL1-260C
 - Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
 - The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
 - The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
 - The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles
 Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:
 Qualified Pb-Free(SMT) and Green

TI Qualification ID: 20210308-139022

For questions regarding this notice, e-mails can be sent to the contact below or your local Field Sales Representative.

Location	E-Mail
WW Change Management Team	PCN_ww_admin_team@list.ti.com

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